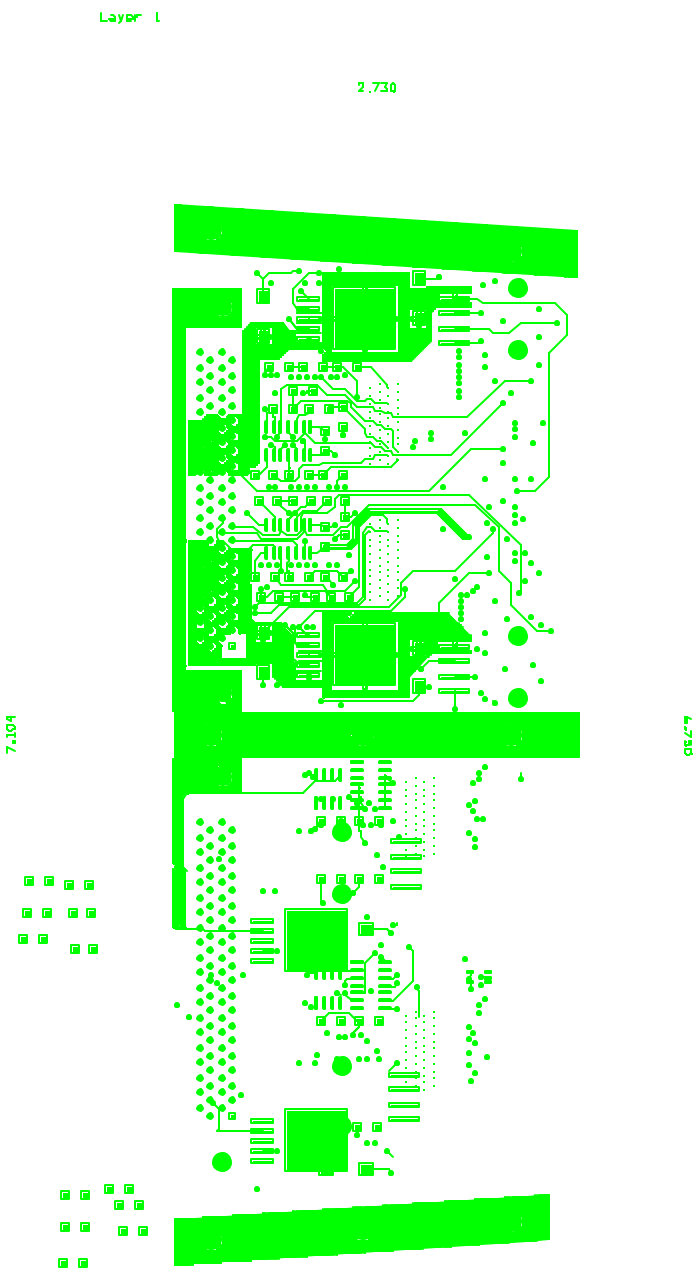
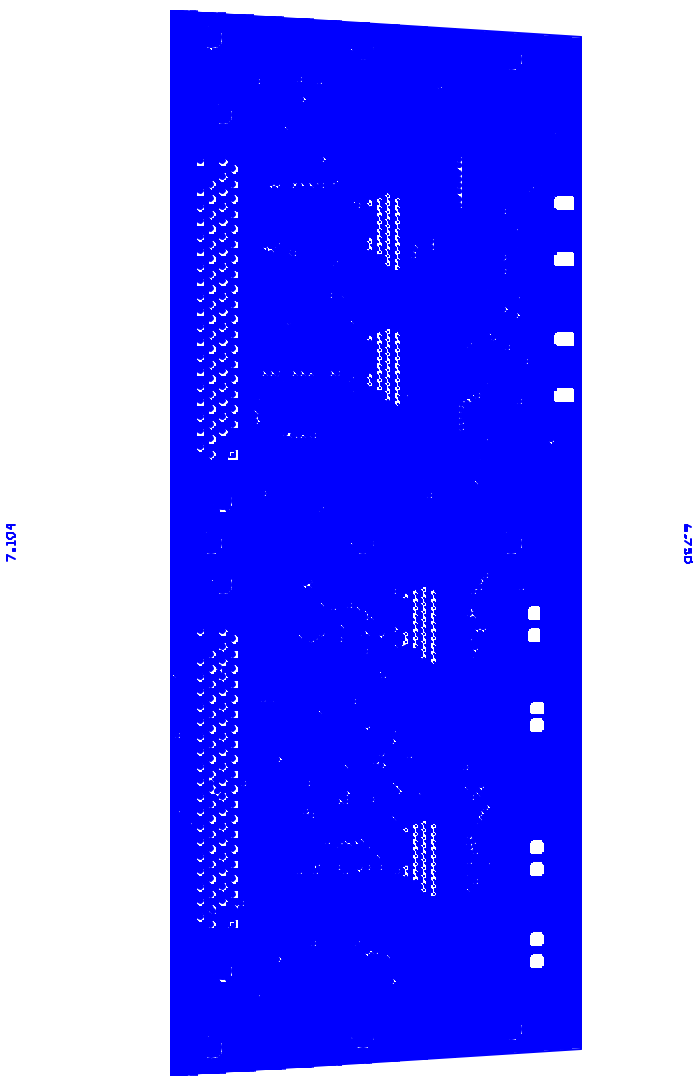

Layer 1
2.730
7.104
6.750

Layers 2 and 5

2.730



Layer 3

2.730

7.194

6.750

Layer 4

2.730

7.194

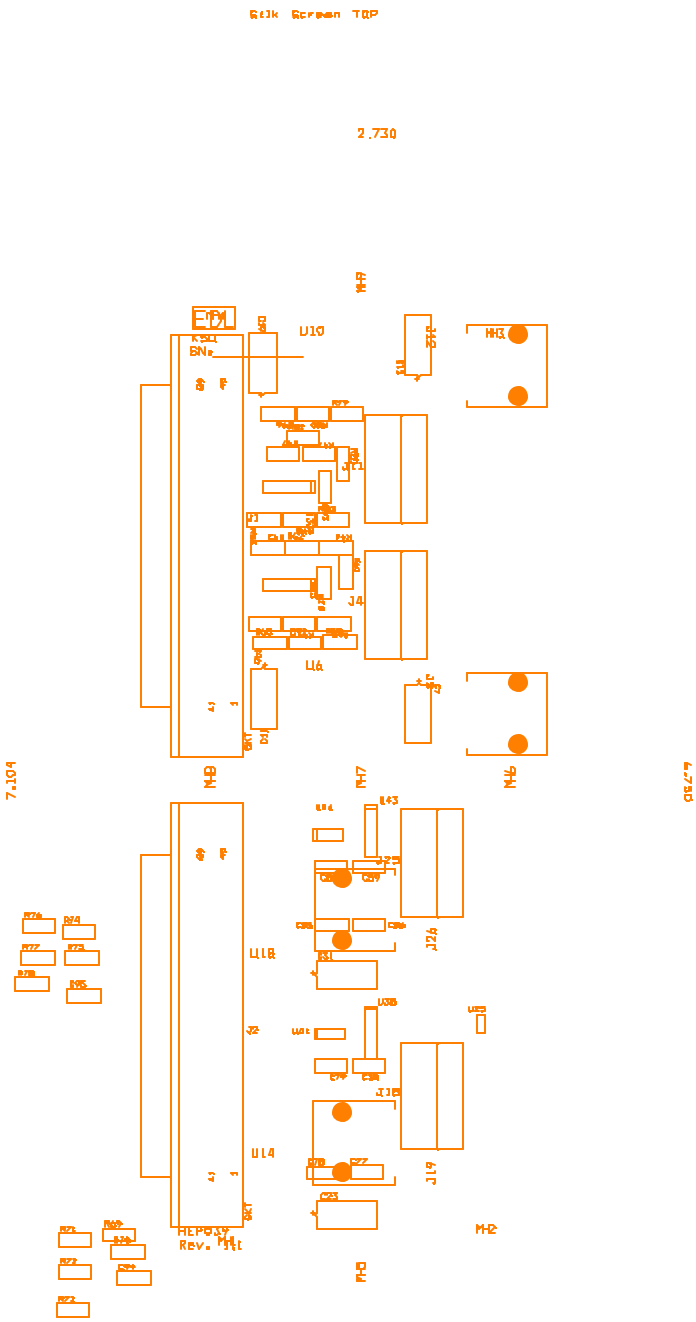
4.750

Layer 6

2.730

7.194

4.750


Silk Screen TOP
2.730
7.104
4.750
U10
U6
U18
U14
J4
J26
J19
MH3
MH7
MH2
HEP039
Rev. M1

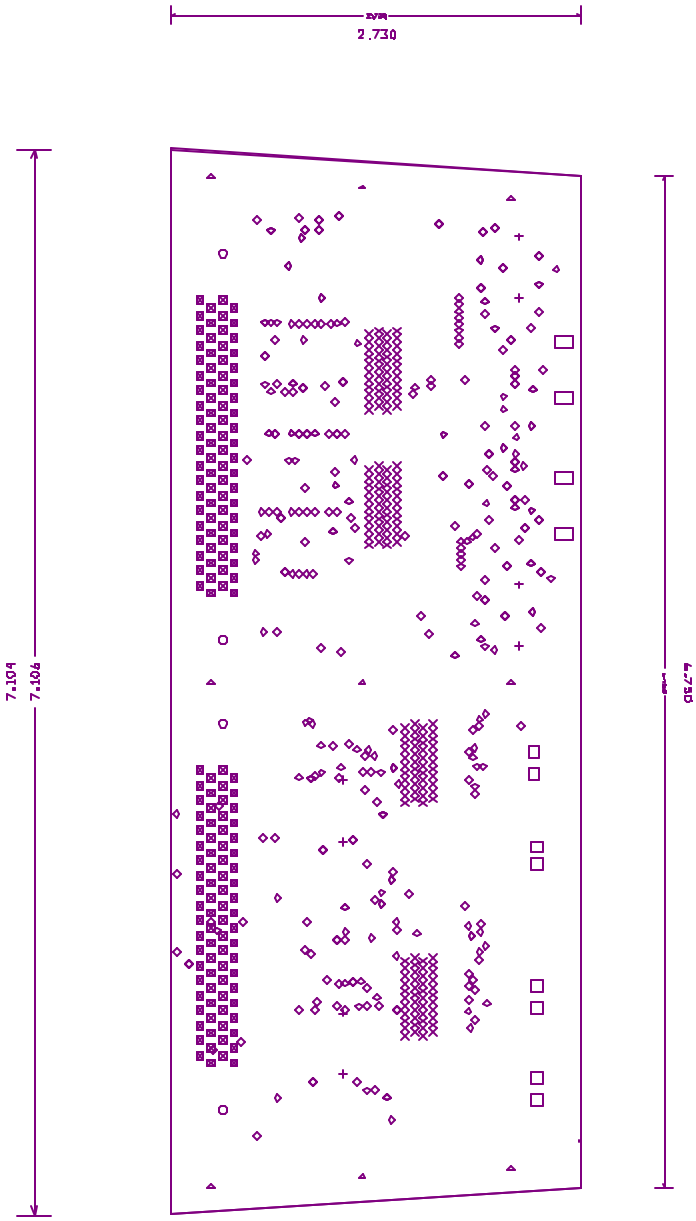
Silk Screen BOT
2.730
7.104
0.270

Board Name: Adaptor Card
Board Number: HEP839 Rev 1.1
Notes:

1. Board Material: FR4
   Multilayer - 4 layers
   .062" finished thickness
   .5 oz copper
2. Drilling:
   See drill chart; all hole diameters
   specified are finished hole sizes.
3. Plating:
   Selective Solder Plates Plated through
   holes copper .0027" minimum thickness.
   Pad areas 60/40 tin-lead .0001-.0003 minimum.
4. Trace Width and Spacing:
   Minimum trace widths .005"
   Minimum clearance: .005"
5. Number of SM Pads: Top : 232 Bottom: 688
6. Controlled Impedance:
   75 ohm characteristic impedance for
   trace widths of .045" on all signal layers.

7. Solder Mask:
   Top side and bottom side solder mask - green
8. Silk Screen:
   Top side and bottom side silk screen - white
9. Final Fabrication: Fabricate to dimensions shown.
10. Do not scale drawing.
11. Remove all burrs and sharp edges.
12. Materials Supplied:
    NC Drill Files
    Gerber Photoplot Files
13. There are 16 dimensioned slot cutouts.

Drill Drawing



DRILL CHART				
SYM	DIAM	TOL	QTY	NOTE
×	0.018	+.003,-0	176	
◇	0.020	+.003,-0	285	
⊠	0.034	+.003,-0	160	
○	0.109	+/- .005	4	
△	0.120	+/- .005	9	
+	0.134		8	NON-PLATED
TOTAL			642	

Note: Dimensions are in inches.